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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	248
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-2fgg484i

The SRAM blocks are arranged in a column on the west side of the tile (Figure 1-6 on page 1-4).

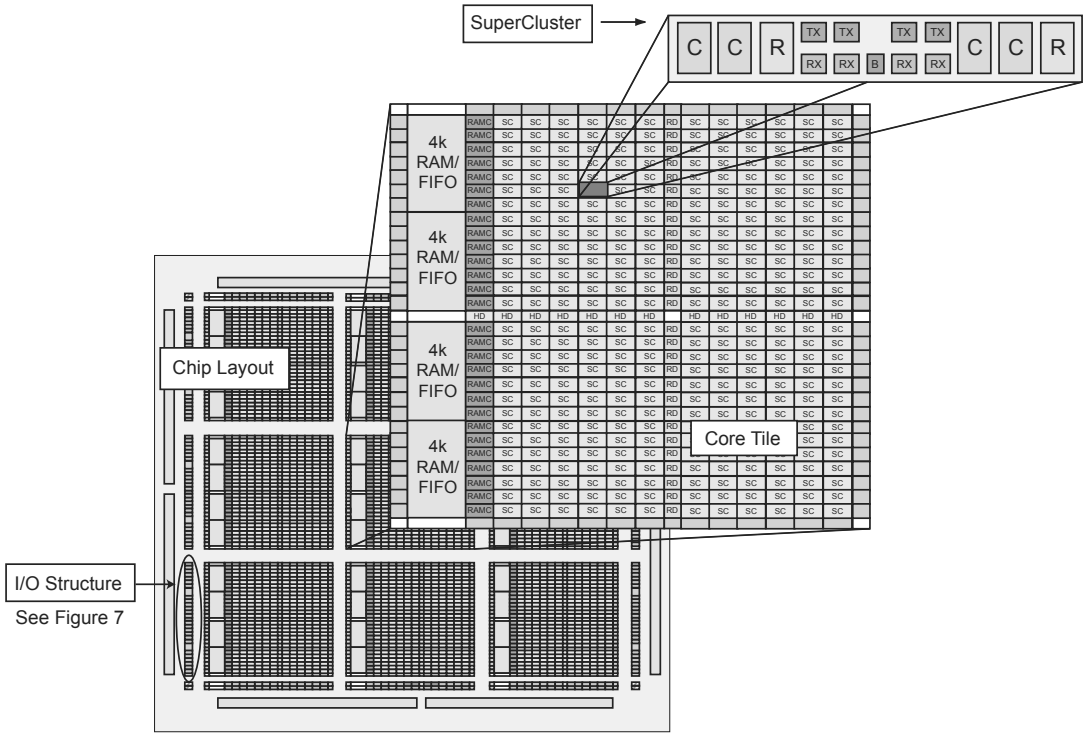


Figure 1-6 • **AX Device Architecture (AX1000 shown)**

Embedded Memory

As mentioned earlier, each core tile has either three (in a smaller tile) or four (in the regular tile) embedded SRAM blocks along the west side, and each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are: 128x36, 256x18, 512x9, 1kx4, 2kx2 or 4kx1 bits. The individual blocks have separate read and write ports that can be configured with different bit widths on each port. For example, data can be written in by eight and read out by one.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using core logic modules. The FIFO width and depth are programmable. The FIFO also features programmable ALMOST-EMPTY (AEMPTY) and ALMOST-FULL (AFULL) flags in addition to the normal EMPTY and FULL flags. In addition to the flag logic, the embedded FIFO control unit also contains the counters necessary for the generation of the read and write address pointers as well as control circuitry to prevent metastability and erroneous operation. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

I/O Logic

The Axcelerator family of FPGAs features a flexible I/O structure, supporting a range of mixed voltages with its bank-selectable I/Os: 1.5V, 1.8V, 2.5V, and 3.3V. In all, Axcelerator FPGAs support at least 14 different I/O standards (single-ended, differential, voltage-referenced). The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported (see "User I/Os" on page 2-11 for more information). All I/O standards are available in each bank.

Each I/O module has an input register (InReg), an output register (OutReg), and an enable register (EnReg) (Figure 1-7 on page 1-5). An I/O Cluster includes two I/O modules, four RX modules, two TX modules, and a buffer (B) module.

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

User I/Os[2]

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer's PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

2. *Do not use an external resister to pull the I/O above V_{CCI} for a higher logic "1" voltage level. The desired higher logic "1" voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI}.*

I/O Clusters

Each I/O cluster incorporates two I/O modules, four RX modules, two TX modules, and a buffer module. In turn, each I/O module contains one Input Register (InReg), one Output Register (OutReg), and one Enable Register (EnReg) (Figure 2-5).

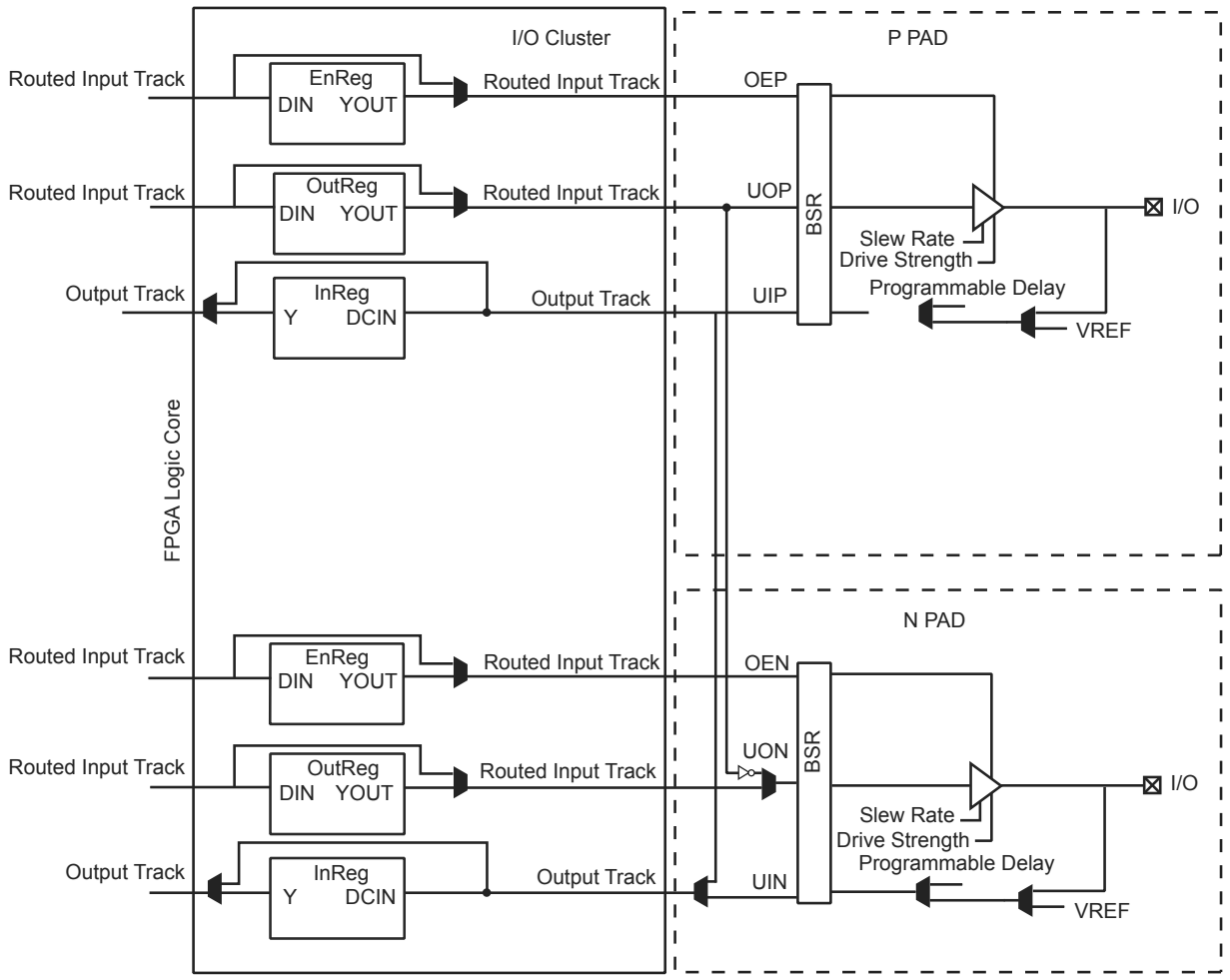


Figure 2-5 • **I/O Cluster Interface**

Using an I/O Register

To access the I/O registers, registers must be instantiated in the netlist and then connected to the I/Os. Usage of each I/O register (register combining) is individually controlled and can be selected/deselected using the PinEditor tool in the Designer software. I/O register combining can also be controlled at the device level, affecting all I/Os. Please note, the I/O register option is deselected by default in any given design.[4]

In addition, Designer software provides a global option to enable/disable the usage of registers in the I/Os. This option is design-specific. The setting for each individual I/O overrides this global option. Furthermore, the *global set fuse* option in the Designer software, when checked, causes all I/O registers to output logic High at device power-up.

4. Please note that register combining for multi fanout nets is not supported.

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 4 (24 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		10.45		11.90		13.99	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		10.61		12.08		14.21	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		10.47		11.93		14.02	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.92		1.94		1.94	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.57		2.58		2.59	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, –3.5 V in undershoot, and 7.1 V in overshoot.

***Table 2-33* • DC Input and Output Levels**

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
PCI	–0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	–0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

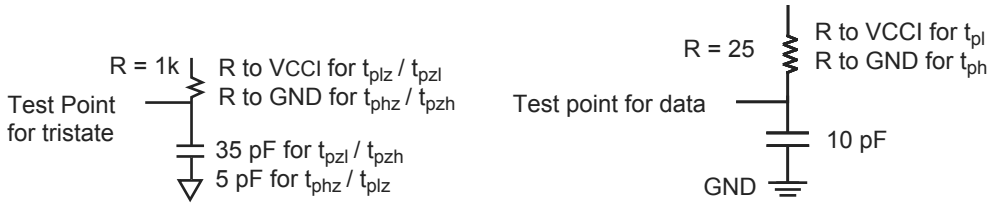


***Figure 2-18 •* AC Test Loads**

***Table 2-34* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-65 • AX125 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.35	0.40	0.47	ns
t_{RD2}	Routing delay for FO2	0.38	0.43	0.51	ns
t_{RD3}	Routing delay for FO3	0.43	0.48	0.57	ns
t_{RD4}	Routing delay for FO4	0.48	0.55	0.64	ns
t_{RD5}	Routing delay for FO5	0.55	0.62	0.73	ns
t_{RD6}	Routing delay for FO6	0.64	0.72	0.85	ns
t_{RD7}	Routing delay for FO7	0.79	0.89	1.05	ns
t_{RD8}	Routing delay for FO8	0.88	0.99	1.17	ns
t_{RD16}	Routing delay for FO16	1.49	1.69	1.99	ns
t_{RD32}	Routing delay for FO32	2.32	2.63	3.10	ns

Table 2-66 • AX250 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.39	0.45	0.53	ns
t_{RD2}	Routing delay for FO2	0.41	0.46	0.54	ns
t_{RD3}	Routing delay for FO3	0.48	0.55	0.64	ns
t_{RD4}	Routing delay for FO4	0.56	0.63	0.75	ns
t_{RD5}	Routing delay for FO5	0.60	0.68	0.80	ns
t_{RD6}	Routing delay for FO6	0.84	0.96	1.13	ns
t_{RD7}	Routing delay for FO7	0.90	1.02	1.20	ns
t_{RD8}	Routing delay for FO8	1.00	1.13	1.33	ns
t_{RD16}	Routing delay for FO16	2.17	2.46	2.89	ns
t_{RD32}	Routing delay for FO32	3.55	4.03	4.74	ns

The HM and CM modules can select between:

- The HCLK or CLK source respectively
- A local signal routed on generic routing resources

This allows each core tile to have eight clocks independent of the other core tiles in the device.

Both HCLK and CLK are segmentable, meaning that individual branches of the global resource can be used independently.

Like the HM and CM modules, the HD and RD modules can select between:

- The HCLK or CLK source from the HM or CM module respectively
- A local signal routed on generic routing resources

The AX architecture is capable of supporting a large number of local clocks—24 segments per HCLK driving north-south and 28 segments per CLK driving east-west per core tile.

Microsemi's Designer software's place-and-route takes advantage of the segmented clock structure found in Axcelerator devices by turning off any unused clock segments. This results in not only better performance but also lower power consumption.

Global Resource Access Macros

Global resources can be driven by one of three sources: external pad(s), an internal net, or the output of a PLL. These connections can be made by using one of three types of macros: CLKBUF, CLKINT, and PLLCLK.

CLKBUF and HCLKBUF

CLKBUF (HCLKBUF) is used to drive a CLK (HCLK) from external pads. These macros can be used either generically or with the specific I/O standard desired (e.g. CLKBUF_LVCMOS25, HCLKBUF_LVDS, etc.) (Figure 2-42).

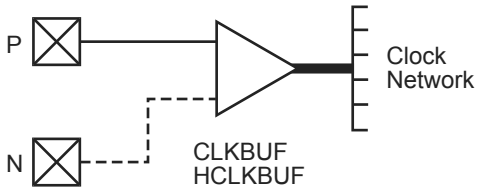


Figure 2-42 • **CLKBUF and HCLKBUF**

Package pins CLKEP and CLKEN are associated with CLKE; package pins HCLKAP and HCLKAN are associated with HCLKA, etc.

Note that when CLKBUF (HCLKBUF) is used with a single-ended I/O standard, it must be tied to the P-pad of the CLK (HCLK) package pin. In this case, the CLK (HCLK) N-pad can be used for user signals.

CLKINT and HCLKINT

CLKINT (HCLKINT) is used to access the CLK (HCLK) resource internally from the user signals (Figure 2-43).

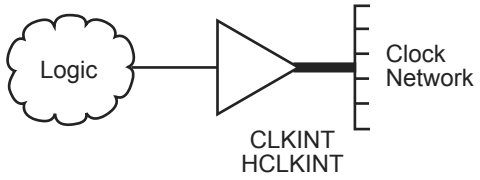


Figure 2-43 • **CLKINT and HCLKINT**

Special PLL Macros

Table 2-84 shows the macros used to connect the RefCLK input and CLK1 and CLK2 outputs using the different routing resources.

***Table 2-84* • PLL Special Macros**

Macro Name	Usage
PLLINT	Connects RefCLK to a regular routed net or a pad.
PLLRCLK	Connects CLK1 or CLK2 to the CLK network.
PLLHCLK	Connects CLK1 or CLK2 to the HCLK network.
PLLOUT	Connects CLK1 or CLK2 to a regular routed net.

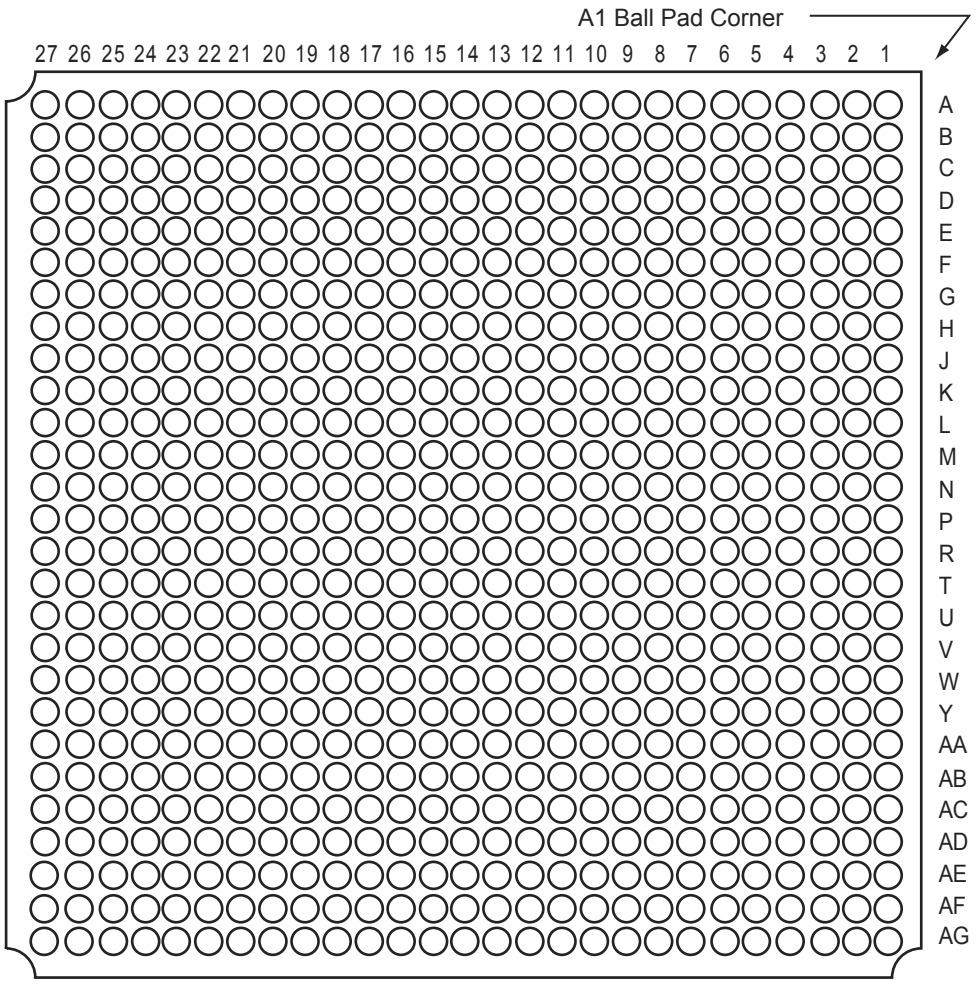
***Table 2-85* • Electrical Specifications**

Parameter	Value	Notes
Frequency Ranges		
Reference Frequency (min.)	14 MHz	Lowest input frequency
Reference Frequency (max.)	200 MHz	Highest input frequency
OSC Frequency (min.)	20 MHz	Lowest output frequency
OSC Frequency (max.)	1 GHz	Highest output frequency
Jitter		
Long-Term Jitter (max.)	1%	Percentage of period, low reference clock frequencies
Long-Term Jitter (max.)	100ps	High reference clock frequencies
Short-Term Jitter (max.)	50ps+1%	Percentage of output frequency
Acquisition Time (lock) from Cold Start		
Acquisition Time (max.)*	400 cycles	Period of low reference clock frequencies
Acquisition Time (max.)*	1.5 µs	High reference clock frequencies
Power Consumption		
Analog Supply Current (low freq.)	200 µA	Current at minimum oscillator frequency
Analog Supply Current (high freq.)	200 µA	Frequency-dependent current
Digital Supply Current (low freq.)	0.5 µA/MHz	Current at maximum oscillator frequency, unloaded
Digital Supply Current (high freq.)	1 µA/MHz	Frequency-dependent current
Duty Cycle		
Minimum Output Duty Cycle	45%	
Maximum Output Duty Cycle	55%	

*Note: *The lock bit remains Low until RefCLK reaches the minimum input frequency.*

3 – Package Pin Assignments

BG729



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

BG729	
AX1000 Function	Pin Number
GND	B27
GND	B3
GND	C1
GND	C2
GND	C25
GND	C26
GND	C27
GND	C3
GND	E27
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17

BG729	
AX1000 Function	Pin Number
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND/LP	J8
NC	U3
PRA	J14
PRB	D14
PRC	V14
PRD	AB14
TCK	E4
TDI	D4
TDO	J9
TMS	H8
TRST	E3
VCCA	AA21
VCCA	AD5
VCCA	E1
VCCA	G22
VCCA	K10

BG729	
AX1000 Function	Pin Number
VCCA	K11
VCCA	K17
VCCA	K18
VCCA	L10
VCCA	L18
VCCA	U10
VCCA	U18
VCCA	V10
VCCA	V11
VCCA	V17
VCCA	V18
VCCPLA	A13
VCCPLB	J13
VCCPLC	B15
VCCPLD	C15
VCCPLE	AG14
VCCPLF	AF14
VCCPLG	AB13
VCCPLH	AG13
VCCDA	A11
VCCDA	AB12
VCCDA	AC12
VCCDA	AC25
VCCDA	AD16
VCCDA	AD17
VCCDA	E16
VCCDA	E2
VCCDA	E24
VCCDA	F12
VCCDA	F16
VCCDA	F7
VCCDA	K14
VCCDA	P10
VCCDA	P18
VCCDA	W14
VCCDA	W9
VCCIB0	A4

FG324	
AX125 Function	**Pin Number**
IO50NB4F4/CLKFN	U9
IO50PB4F4/CLKFP	U10
Bank 5	
IO51NB5F5/CLKGN	R8
IO51PB5F5/CLKGP	R9
IO52NB5F5/CLKHN	T7
IO52PB5F5/CLKHP	T8
IO53NB5F5	U6
IO53PB5F5	U7
IO54NB5F5	V8
IO54PB5F5	V9
IO55NB5F5	V6
IO55PB5F5	V7
IO56NB5F5	U4
IO56PB5F5	U5
IO57NB5F5	T4
IO57PB5F5	T5
IO58NB5F5	V4
IO58PB5F5	V5
IO59NB5F5	V2
IO59PB5F5	V3
Bank 6	
IO60NB6F6	P5
IO60PB6F6	P6
IO61NB6F6	T2
IO61PB6F6	U3
IO62NB6F6	T1
IO62PB6F6	U1
IO63NB6F6	P1
IO63PB6F6	R1
IO64NB6F6	R3
IO64PB6F6	P3
IO65NB6F6	P2
IO65PB6F6	R2
IO66NB6F6	M3

FG324	
AX125 Function	**Pin Number**
IO66PB6F6	N3
IO67NB6F6	M2
IO67PB6F6	N2
IO68NB6F6	M1
IO68PB6F6	N1
IO69NB6F6	K4
IO69PB6F6	L4
IO70NB6F6	K1
IO70PB6F6	L1
IO71NB6F6	K3
IO71PB6F6	L3
Bank 7	
IO72NB7F7	H4
IO72PB7F7	J4
IO73NB7F7	K2
IO73PB7F7	L2
IO74NB7F7	H2
IO74PB7F7	H1
IO75NB7F7	H3
IO75PB7F7	J3
IO76NB7F7	F2
IO76PB7F7	G2
IO77NB7F7	F1
IO77PB7F7	G1
IO78NB7F7	D2
IO78PB7F7	E2
IO79NB7F7	F3
IO79PB7F7	G3
IO80NB7F7	E3
IO80PB7F7	E4
IO81NB7F7	D1
IO81PB7F7	E1
IO82NB7F7	D3
IO82PB7F7	C2
IO83NB7F7	B1

FG324	
AX125 Function	**Pin Number**
IO83PB7F7	C1
Dedicated I/O	
VCCDA	F5
GND	A1
GND	A18
GND	B17
GND	B2
GND	C16
GND	C3
GND	E16
GND	F13
GND	F6
GND	G12
GND	G7
GND	H10
GND	H11
GND	H8
GND	H9
GND	J10
GND	J11
GND	J8
GND	J9
GND	K10
GND	K11
GND	K8
GND	K9
GND	L10
GND	L11
GND	L8
GND	L9
GND	M12
GND	M7
GND	N13
GND	N6
GND	R14

FG484	
AX250 Function	**Pin Number**
IO104PB6F6	N4
IO105NB6F6	M5
IO105PB6F6	N5
IO106NB6F6	M3
IO106PB6F6	N3
Bank 7	
IO107NB7F7	M2
IO107PB7F7	N1
IO108NB7F7	L3
IO108PB7F7	L2
IO109NB7F7	K2
IO109PB7F7	K1
IO110NB7F7	K5
IO110PB7F7	L5
IO111NB7F7	K6
IO111PB7F7	L6
IO112NB7F7	K4
IO112PB7F7	K3
IO113NB7F7	K7
IO113PB7F7	L7
IO114NB7F7	H1
IO114PB7F7	J1
IO115NB7F7	H2
IO115PB7F7	J2
IO116NB7F7	H4
IO116PB7F7	J4
IO117NB7F7	H5
IO117PB7F7	J5
IO118NB7F7	F2
IO118PB7F7	G2
IO119NB7F7	H6
IO119PB7F7	J6
IO120NB7F7	F1
IO120PB7F7	G1
IO121NB7F7	F4
IO121PB7F7	G4

FG484	
AX250 Function	**Pin Number**
IO122NB7F7	G5
IO122PB7F7	G6
IO123NB7F7	F5
IO123PB7F7	E4
Dedicated I/O	
VCCDA	H7
GND	A1
GND	A11
GND	A12
GND	A2
GND	A21
GND	A22
GND	AA1
GND	AA2
GND	AA21
GND	AA22
GND	AB1
GND	AB11
GND	AB12
GND	AB2
GND	AB21
GND	AB22
GND	B1
GND	B2
GND	B21
GND	B22
GND	C20
GND	C3
GND	D19
GND	D4
GND	E18
GND	E5
GND	G18
GND	H15
GND	H8
GND	J14

FG484	
AX250 Function	**Pin Number**
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	L1
GND	L10
GND	L11
GND	L12
GND	L13
GND	L22
GND	M1
GND	M10
GND	M11
GND	M12
GND	M13
GND	M22
GND	N10
GND	N11
GND	N12
GND	N13
GND	P14
GND	P9
GND	R15
GND	R8
GND	U16
GND	U6
GND	V18
GND	V5
GND	W19
GND	W4
GND	Y20
GND	Y3
GND/LP	G7
NC	A17
NC	A18

FG484	
AX250 Function	**Pin Number**
NC	A19
NC	A4
NC	A5
NC	AA11
NC	AA12
NC	AA18
NC	AA19
NC	AA4
NC	AB16
NC	AB17
NC	AB4
NC	AB7
NC	AB8
NC	B11
NC	B12
NC	B17
NC	B18
NC	B19
NC	B4
NC	B5
NC	C10
NC	C11
NC	C14
NC	C15
NC	C18
NC	C19
NC	D1
NC	D2
NC	D21
NC	D3
NC	E1
NC	E2
NC	E21
NC	E3
NC	F22
NC	F3

FG484	
AX250 Function	**Pin Number**
NC	G22
NC	G3
NC	H3
NC	J3
NC	K21
NC	K22
NC	N22
NC	P22
NC	R19
NC	R22
NC	T1
NC	T22
NC	U1
NC	U2
NC	U21
NC	U22
NC	V1
NC	V2
NC	V21
NC	V22
NC	V3
NC	W1
NC	W2
NC	W21
NC	W22
NC	W3
NC	Y10
NC	Y11
NC	Y12
NC	Y13
NC	Y15
NC	Y16
NC	Y17
NC	Y18
NC	Y8
NC	Y9

FG484	
AX250 Function	**Pin Number**
PRA	G11
PRB	F11
PRC	T12
PRD	U12
TCK	G8
TDI	F9
TDO	F7
TMS	F6
TRST	F8
VCCA	G17
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J7
VCCA	K14
VCCA	K9
VCCA	L14
VCCA	L9
VCCA	M14
VCCA	M9
VCCA	N14
VCCA	N9
VCCA	P10
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10

FG1152	
AX2000 Function	Pin Number
GND	N1
GND	N13
GND	N22
GND	N34
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	P20
GND	P21
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R20
GND	R21
GND	R3
GND	R32
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T20
GND	T21
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18

FG1152	
AX2000 Function	Pin Number
GND	U19
GND	U20
GND	U21
GND	U30
GND	U5
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V20
GND	V21
GND	V30
GND	V5
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18
GND	W19
GND	W20
GND	W21
GND	Y14
GND	Y15
GND	Y16
GND	Y17
GND	Y18
GND	Y19
GND	Y20
GND	Y21
GND	Y3
GND	Y32
GND/LP	G6
NC	A17

FG1152	
AX2000 Function	Pin Number
NC	A26
NC	AB2
NC	AB33
NC	AC34
NC	AD3
NC	AD34
NC	AE31
NC	AE33
NC	AE34
NC	AF1
NC	AF34
NC	AG2
NC	AG4
NC	AH1
NC	AH2
NC	AH31
NC	AH32
NC	AH34
NC	AJ1
NC	AJ2
NC	AJ3
NC	AJ31
NC	AJ32
NC	AJ33
NC	AJ34
NC	AJ4
NC	AL29
NC	AM19
NC	AM7
NC	AN13
NC	AN17
NC	AN25
NC	AN27
NC	AN8
NC	AP17

CQ208	
AX250 Function	Pin Number
Bank 0	
IO02NB0F0	197
IO03NB0F0	198
IO03PB0F0	199
IO12NB0F0/HCLKAN	191
IO12PB0F0/HCLKAP	192
IO13NB0F0/HCLKBN	185
IO13PB0F0/HCLKBP	186
Bank 1	
IO14NB1F1/HCLKCN	180
IO14PB1F1/HCLKCP	181
IO15NB1F1/HCLKDN	174
IO15PB1F1/HCLKDP	175
IO16NB1F1	170
IO16PB1F1	171
IO24NB1F1	165
IO24PB1F1	166
IO26NB1F1	161
IO26PB1F1	162
IO27NB1F1	159
IO27PB1F1	160
Bank 2	
IO29NB2F2	151
IO29PB2F2	153
IO30NB2F2	152
IO30PB2F2	154
IO31PB2F2	148
IO32NB2F2	146
IO32PB2F2	147
IO34NB2F2	144
IO34PB2F2	145
IO39NB2F2	139
IO39PB2F2	140
IO40PB2F2	141
IO41NB2F2	137
IO41PB2F2	138
IO43NB2F2	132

CQ208	
AX250 Function	Pin Number
IO43PB2F2	134
IO44NB2F2	131
IO44PB2F2	133
Bank 3	
IO45NB3F3	127
IO45PB3F3	129
IO46NB3F3	126
IO46PB3F3	128
IO48NB3F3	122
IO48PB3F3	123
IO50NB3F3	120
IO50PB3F3	121
IO55NB3F3	116
IO55PB3F3	117
IO57NB3F3	114
IO57PB3F3	115
IO59NB3F3	110
IO59PB3F3	111
IO60NB3F3	108
IO60PB3F3	109
IO61NB3F3	106
IO61PB3F3	107
Bank 4	
IO62NB4F4	100
IO62PB4F4	103
IO63NB4F4	101
IO63PB4F4	102
IO64NB4F4	96
IO64PB4F4	97
IO72NB4F4	91
IO72PB4F4	92
IO74NB4F4/CLKEN	87
IO74PB4F4/CLKEP	88
IO75NB4F4/CLKFN	81
IO75PB4F4/CLKFP	82
Bank 5	
IO76NB5F5/CLKGN	76

CQ208	
AX250 Function	Pin Number
IO76PB5F5/CLKGP	77
IO77NB5F5/CLKHN	70
IO77PB5F5/CLKHP	71
IO78NB5F5	66
IO78PB5F5	67
IO86NB5F5	62
IO87NB5F5	60
IO87PB5F5	61
IO88NB5F5	56
IO88PB5F5	57
IO89NB5F5	54
IO89PB5F5	55
Bank 6	
IO91NB6F6	47
IO91PB6F6	49
IO92NB6F6	48
IO92PB6F6	50
IO93NB6F6	42
IO93PB6F6	43
IO94PB6F6	44
IO96NB6F6	40
IO96PB6F6	41
IO101NB6F6	35
IO101PB6F6	36
IO102PB6F6	37
IO103NB6F6	33
IO103PB6F6	34
IO105NB6F6	28
IO105PB6F6	30
IO106NB6F6	27
IO106PB6F6	29
Bank 7	
IO107NB7F7	23
IO107PB7F7	25
IO108NB7F7	22
IO108PB7F7	24
IO110NB7F7	18

CQ352	
AX500 Function	Pin Number
IO87PB4F8	171
IO89NB4F8	166
IO89PB4F8	167
IO94NB4F9	164
IO94PB4F9	165
IO95NB4F9	160
IO95PB4F9	161
IO97NB4F9	158
IO97PB4F9	159
IO99NB4F9	154
IO99PB4F9	155
IO100NB4F9	146
IO100PB4F9	147
IO101NB4F9	152
IO101PB4F9	153
IO103NB4F9/CLKEN	142
IO103PB4F9/CLKEP	143
IO104NB4F9/CLKFN	136
IO104PB4F9/CLKFP	137
Bank 5	
IO105NB5F10/CLKGN	128
IO105PB5F10/CLKGP	129
IO106NB5F10/CLKHN	122
IO106PB5F10/CLKHP	123
IO107NB5F10	118
IO107PB5F10	119
IO114NB5F11	112
IO114PB5F11	113
IO115NB5F11	110
IO115PB5F11	111
IO116NB5F11	106
IO116PB5F11	107
IO117NB5F11	104
IO117PB5F11	105
IO119NB5F11	100

CQ352	
AX500 Function	Pin Number
IO119PB5F11	101
IO121NB5F11	98
IO121PB5F11	99
IO123NB5F11	94
IO123PB5F11	95
IO125NB5F11	92
IO125PB5F11	93
Bank 6	
IO126PB6F12	86
IO127NB6F12	84
IO127PB6F12	85
IO129NB6F12	82
IO129PB6F12	83
IO131NB6F12	78
IO131PB6F12	79
IO133NB6F12	76
IO133PB6F12	77
IO134NB6F12	72
IO134PB6F12	73
IO135NB6F12	70
IO135PB6F12	71
IO137NB6F13	66
IO137PB6F13	67
IO138NB6F13	64
IO138PB6F13	65
IO139NB6F13	60
IO139PB6F13	61
IO141NB6F13	54
IO141PB6F13	55
IO142NB6F13	58
IO142PB6F13	59
IO143NB6F13	52
IO143PB6F13	53
IO145NB6F13	48
IO145PB6F13	49

CQ352	
AX500 Function	Pin Number
IO146NB6F13	46
IO146PB6F13	47
Bank 7	
IO147NB7F14	40
IO147PB7F14	41
IO148NB7F14	42
IO148PB7F14	43
IO149NB7F14	36
IO149PB7F14	37
IO151NB7F14	30
IO151PB7F14	31
IO152NB7F14	34
IO152PB7F14	35
IO153NB7F14	28
IO153PB7F14	29
IO155NB7F14	24
IO155PB7F14	25
IO157NB7F14	22
IO157PB7F14	23
IO159NB7F15	16
IO159PB7F15	17
IO160NB7F15	18
IO160PB7F15	19
IO161NB7F15	12
IO161PB7F15	13
IO163NB7F15	10
IO163PB7F15	11
IO165NB7F15	6
IO165PB7F15	7
IO167NB7F15	4
IO167PB7F15	5
Dedicated I/O	
GND	1
GND	9
GND	15

CQ352	
AX500 Function	Pin Number
GND	21
GND	27
GND	33
GND	39
GND	45
GND	51
GND	57
GND	63
GND	69
GND	75
GND	81
GND	88
GND	89
GND	97
GND	103
GND	109
GND	115
GND	121
GND	133
GND	145
GND	151
GND	157
GND	163
GND	169
GND	176
GND	177
GND	186
GND	192
GND	198
GND	204
GND	210
GND	216
GND	222
GND	228
GND	234

CQ352	
AX500 Function	Pin Number
GND	240
GND	246
GND	252
GND	258
GND	264
GND	265
GND	274
GND	280
GND	286
GND	292
GND	298
GND	310
GND	322
GND	330
GND	334
GND	340
GND	345
GND/LP	352
NC	91
NC	117
NC	130
NC	131
NC	148
NC	174
NC	268
NC	294
NC	307
NC	308
NC	327
NC	328
PRA	312
PRB	311
PRC	135
PRD	134
TCK	349

CQ352	
AX500 Function	Pin Number
TDI	348
TDO	347
TMS	350
TRST	351
VCCA	3
VCCA	14
VCCA	32
VCCA	56
VCCA	74
VCCA	87
VCCA	102
VCCA	114
VCCA	150
VCCA	162
VCCA	175
VCCA	191
VCCA	209
VCCA	233
VCCA	251
VCCA	263
VCCA	279
VCCA	291
VCCA	329
VCCA	339
VCCDA	2
VCCDA	44
VCCDA	90
VCCDA	116
VCCDA	132
VCCDA	149
VCCDA	178
VCCDA	221
VCCDA	266
VCCDA	293
VCCDA	309

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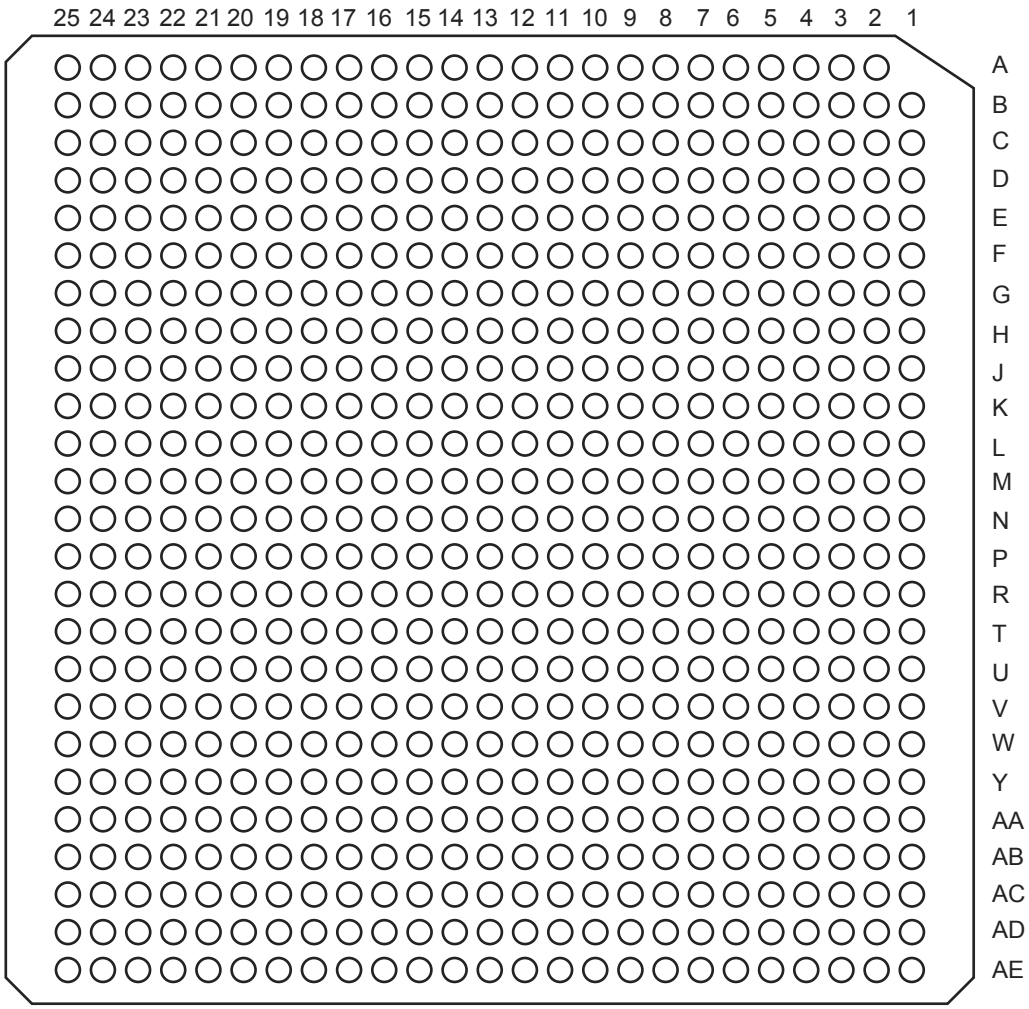

Note

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